

## 32M-Bit (4Mx8 /2Mx16) CMOS MASK ROM

## FEATURES

- Switchable organization  
4,194,304x8(byte mode)  
2,097,152x16(word mode)
- Fast access time  
Random Access Time  
3.3V/3.0V Operation : 100ns(Max.)  
2.5V Operation : 150ns(Max.)
- Supply voltage  
K3N6V(U)1000D-YC(E) : single +3.0V/ single +3.3V  
K3N6S1000D-YC(E) : single +2.5V
- Current consumption  
Operating : 40mA(Max.)  
Standby : 30μA(Max.)
- Fully static operation
- All inputs and outputs TTL compatible
- Three state outputs
- Package
  - K3N6V(U)1000D-YC(E)/K3N6S1000D-YC(E)  
: 48-TSOP1-1218

## GENERAL DESCRIPTION

The K3N6V(U)1000D-YC(E) and K3N6S1000D-YC(E) are fully static mask programmable ROM fabricated using silicon gate CMOS process technology, and is organized either as 4,194,304 x 8 bit(byte mode) or as 2,097,152x16 bit(word mode) depending on BHE voltage level.(See mode selection table)

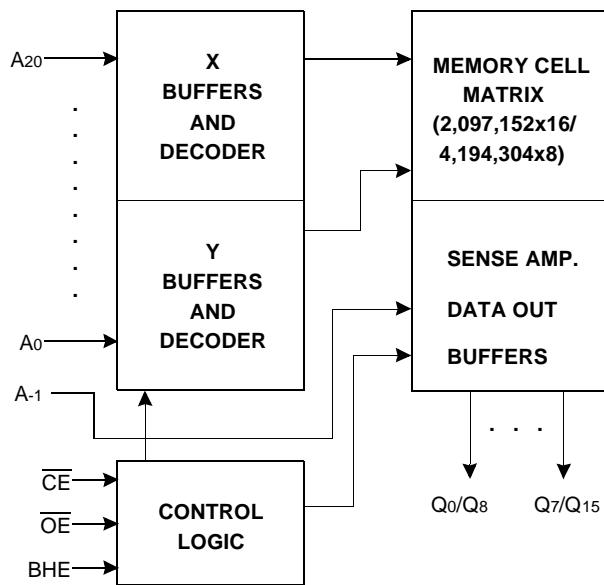
This device operates with low power supply, and all inputs and outputs are TTL compatible.

Because of its asynchronous operation, it requires no external clock assuring extremely easy operation.

It is suitable for use in program memory of microprocessor, and data memory, character generator.

The K3N6V(U)1000D-YC(E) and K3N6S1000D-YC(E) are packaged in a 48-TSOP1.

## FUNCTIONAL BLOCK DIAGRAM



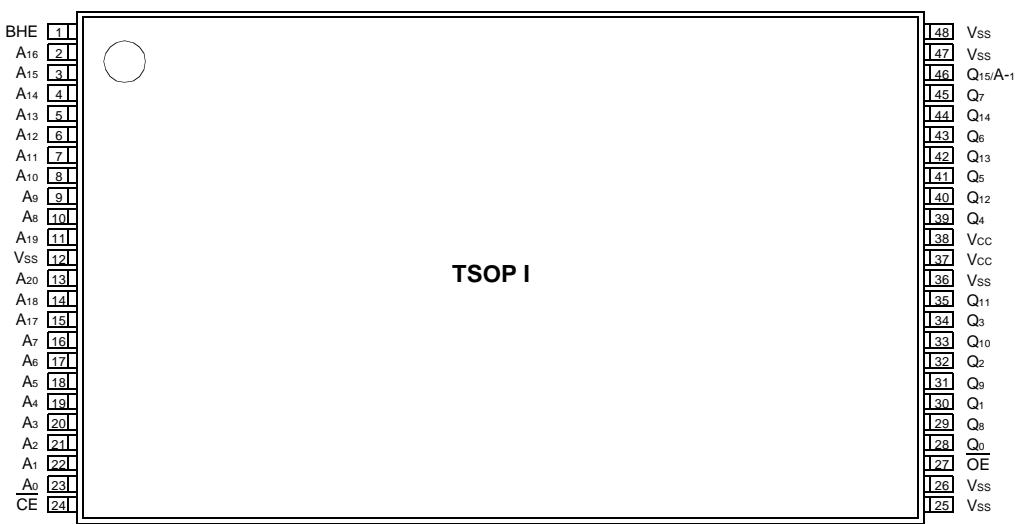
Pin Name	Pin Function
A <sub>0</sub> - A <sub>20</sub>	Address Inputs
Q <sub>0</sub> - Q <sub>14</sub>	Data Outputs
Q <sub>15</sub> / A <sub>-1</sub>	Output 15(Word mode)/ LSB Address(Byte mode)
BHE	Word/Byte selection
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
Vcc	Power
Vss	Ground



## PRODUCT INFORMATION

Product	Operating Temp Range	Vcc Range (Typical)	Speed (ns)
K3N6V(U)1000D-YC	0°C ~ 70°C	3.3V/3.0V	100
K3N6S1000D-YC		2.5V	150
K3N6V(U)1000D-YE	-20°C ~ 85°C	3.3V/3.0V	100
K3N6S1000D-YE		2.5V	150

## PIN CONFIGURATION

K3N6V(U)1000D-YC(E)  
K3N6S1000D-YC(E)

## ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Rating	Unit	Remark
Voltage on Any Pin Relative to	VIN	-0.3 to +4.5	V	-
Temperature Under Bias	TBIAS	-10 to +85	°C	-
Storage Temperature	TSTG	-55 to +150	°C	-
Operating Temperature	TA	0 to +70	°C	K3N6V(U)1000D-YC K3N6S1000D-YC
		-20 to +85	°C	K3N6V(U)1000D-YE K3N6S1000D-YE

NOTE : Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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**RECOMMENDED OPERATING CONDITIONS** (Voltage reference to Vss)

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	Vcc	2.7/3.0	3.0/3.3	3.3/3.6	V
		2.3	2.5	2.7	V
Supply Voltage	Vss	0	0	0	V

**DC CHARACTERISTICS**

Parameter	Symbol	Test Conditions		Min	Max	Unit
Operating Current	Icc	$\overline{CE}=\overline{OE}=V_{IL}$ , all outputs open	$V_{CC}=3.3V \pm 0.3V$	-	40	mA
			$V_{CC}=3.0V \pm 0.3V$	-	35	mA
			$V_{CC}=2.5V \pm 0.2V$	-	30	mA
Standby Current(TTL)	ISB1	K3N6V(U)1000D-YC(E)	$\overline{CE}=V_{IH}$ , all outputs open	-	500	$\mu A$
		K3N6S1000D-YC(E)		-	100	$\mu A$
Standby Current(CMOS)	ISB2	K3N6V(U)1000D-YC(E)	$\overline{CE}=V_{CC}$ , all outputs open	-	30	$\mu A$
		K3N6S1000D-YC(E)		-	5	$\mu A$
Input Leakage Current	ILI	$V_{IN}=0$ to $V_{CC}$		-	10	$\mu A$
Output Leakage Current	ILO	$V_{OUT}=0$ to $V_{CC}$		-	10	$\mu A$
Input High Voltage, All Inputs	VIH			2.0	$V_{CC}+0.3$	V
Input Low Voltage, All Inputs	VIL	K3N6V(U)1000D-YC(E)		-0.3	0.6	V
		K3N6S1000D-YC(E)		-0.3	0.4	V
Output High Voltage Level	VOH	K3N6V(U)1000D-YC(E)	$I_{OH}=-400\mu A$	2.4	-	V
		K3N6S1000D-YC(E)	$I_{OH}=-400\mu A$	2.0	-	V
Output Low Voltage Level	VOL	$I_{OL}=2.1mA$		-	0.4	V

NOTE : Minimum DC Voltage( $V_{IL}$ ) is -0.3V an input pins. During transitions, this level may undershoot to -2.0V for periods <20ns.

Maximum DC voltage on input pins( $V_{IH}$ ) is  $V_{CC}+0.3V$  which, during transitions, may overshoot to  $V_{CC}+2.0V$  for periods <20ns.

**MODE SELECTION**

CE	OE	BHE	Q15/A-1	Mode	Data	Power
H	X	X	X	Standby	High-Z	Standby
L	H	X	X	Operating	High-Z	Active
L	L	H	Output	Operating	$Q_0 \sim Q_{15} : D_{out}$	Active
		L	Input	Operating	$Q_0 \sim Q_7 : D_{out}$ $Q_8 \sim Q_{14} : Hi-Z$	Active

**CAPACITANCE**( $T_A=25^\circ C$ ,  $f=1.0MHz$ )

Item	Symbol	Test Conditions		Min	Max	Unit
Output Capacitance	C <sub>OUT</sub>	$V_{OUT}=0V$		-	12	pF
Input Capacitance	C <sub>IN</sub>	$V_{IN}=0V$		-	12	pF

NOTE : Capacitance is periodically sampled and not 100% tested.



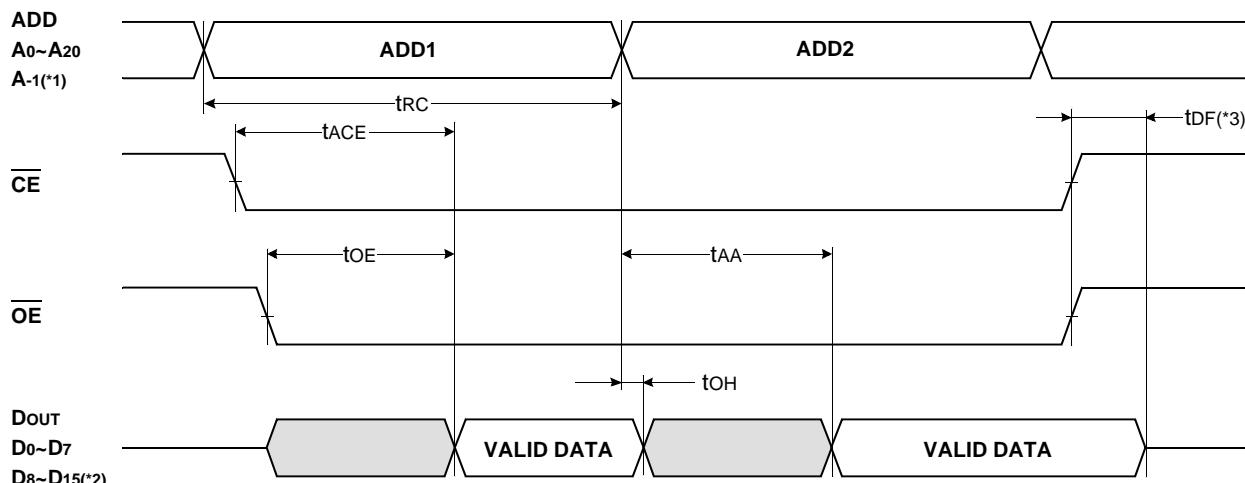
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**AC CHARACTERISTICS**( $V_{CC}=3.3V/3.0V \pm 0.3V$ ,  $V_{CC}=2.5V \pm 0.2V$ , unless otherwise noted.)**TEST CONDITIONS**

Item	Value
Input Pulse Levels	0.45V to 2.4V(at $V_{CC}=3.3V/3.0V$ )
	0.4V to 2.2V (at $V_{CC}=2.5V$ )
Input Rise and Fall Times	10ns
Input and Output timing Levels	1.5V (at $V_{CC}=3.3V/3.0V$ )
	1.1V (at $V_{CC}=2.5V$ )
Output Loads	1 TTL Gate and $C_L=100pF$

**READ CYCLE**

Item	Symbol	$V_{CC}=3.3V/3.0V \pm 0.3V$		$V_{CC}=2.5V \pm 0.2V$		Unit
		Min	Max	Min	Max	
Read Cycle Time	t <sub>RC</sub>	100		150		ns
Chip Enable Access Time	t <sub>ACE</sub>		100		150	ns
Address Access Time	t <sub>AA</sub>		100		150	ns
Output Enable Access Time	t <sub>OE</sub>		50		70	ns
Output or Chip Disable to Output High-Z	t <sub>DF</sub>		20		30	ns
Output Hold from Address Change	t <sub>OH</sub>	0		0		ns

**TIMING DIAGRAM****READ****NOTES :**\*1. Byte Mode only. A-1 is Least Significant Bit Address.(BHE = V<sub>IL</sub>)\*2. Word Mode only.(BHE = V<sub>IH</sub>)\*3. t<sub>DF</sub> is defined as the time at which the outputs achieve the open circuit condition and is not referenced to V<sub>OH</sub> or V<sub>OL</sub> level.

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## PACKAGE DIMENSIONS

(Unit : mm/inch)

